



Material Content Data Sheet



Sales Product Name	BC 860B E6327			Issued		29. August 2013		
MA#	MA000484814							
Package	PG-SOT23-3-11			Weight*		8.80 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.005	0.05		521	
	non noble metal	arsenic	7440-38-2	0.000	0.00		5	
	inorganic material	silicon	7440-21-3	0.039	0.44	0.49	4447	4973
leadframe	non noble metal	chromium	7440-47-3	0.008	0.09		926	
	inorganic material	silicon	7440-21-3	0.001	0.01		62	
	non noble metal	titanium	7440-32-6	0.003	0.03		309	
	non noble metal	copper	7440-50-8	2.704	30.72	30.85	307241	308538
wire	noble metal	gold	7440-57-5	0.012	0.14	0.14	1410	1410
encapsulation	organic material	carbon black	1333-86-4	0.058	0.66		6569	
	plastics	brominated resin	-	0.087	0.99		9854	
	inorganic material	antimonytrioxide	1309-64-4	0.116	1.31		13139	
	plastics	epoxy resin	-	1.243	14.12		141241	
	inorganic material	silicondioxide	60676-86-0	4.279	48.63	65.71	486132	656935
leadfinish	non noble metal	tin	7440-31-5	0.150	1.70	1.70	17001	17001
plating	noble metal	silver	7440-22-4	0.098	1.11	1.11	11143	11143
*deviation	< 10%	Sum in total:			100,00			1000000

Important Remarks:

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